

High Performance Disaggregated Systems through UCle Interconnects and Chiplets

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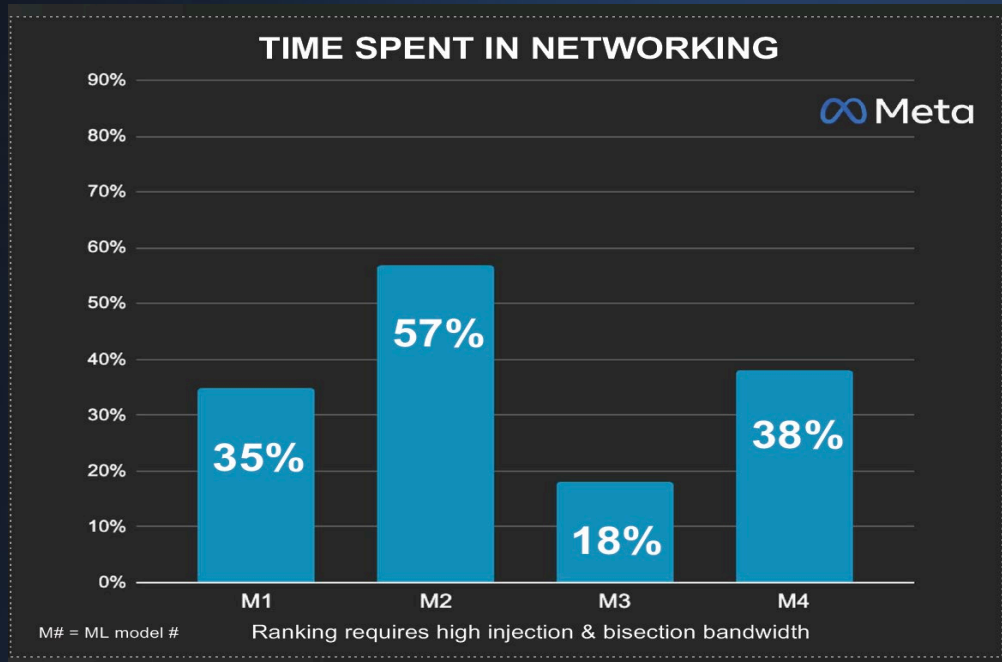
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the Future of Memory and Storage

Deploying AI at Scale - Data Centre Challenges

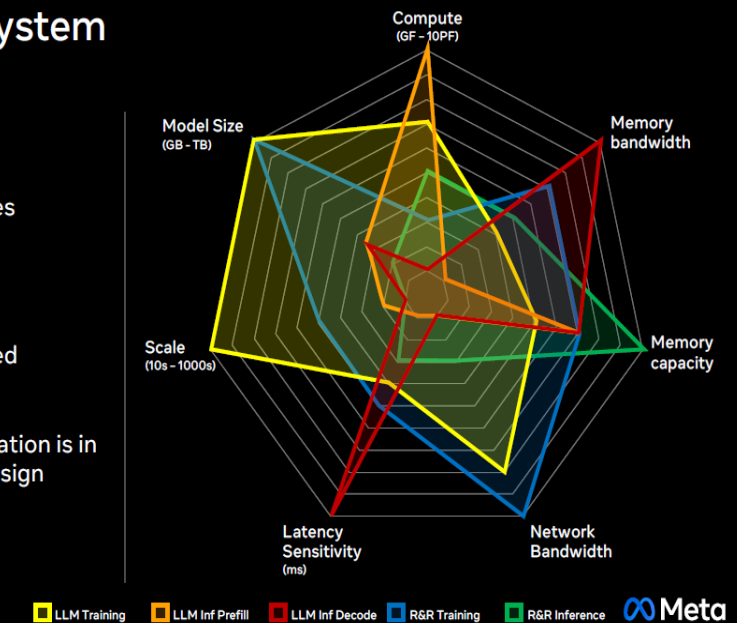
Connectivity



Custom Compute

Diversity of AI system requirements

- Difficult to serve all classes of models with a single system design point
- New models & parallelism techniques put unexpected pressures on AI systems
- The next frontier of innovation is in software/hardware co-design




Source AI Summit : "Leading with Open" Meta

AI requires dedicated hardware with maximum communication bandwidth

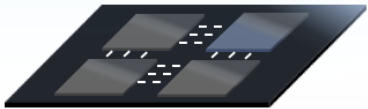
Chipllets - Ushering a New Era of Semiconductors

The New Chiplet Design Paradigm


Chipllets rely on a fabric of dense high-speed die-to-die interconnect



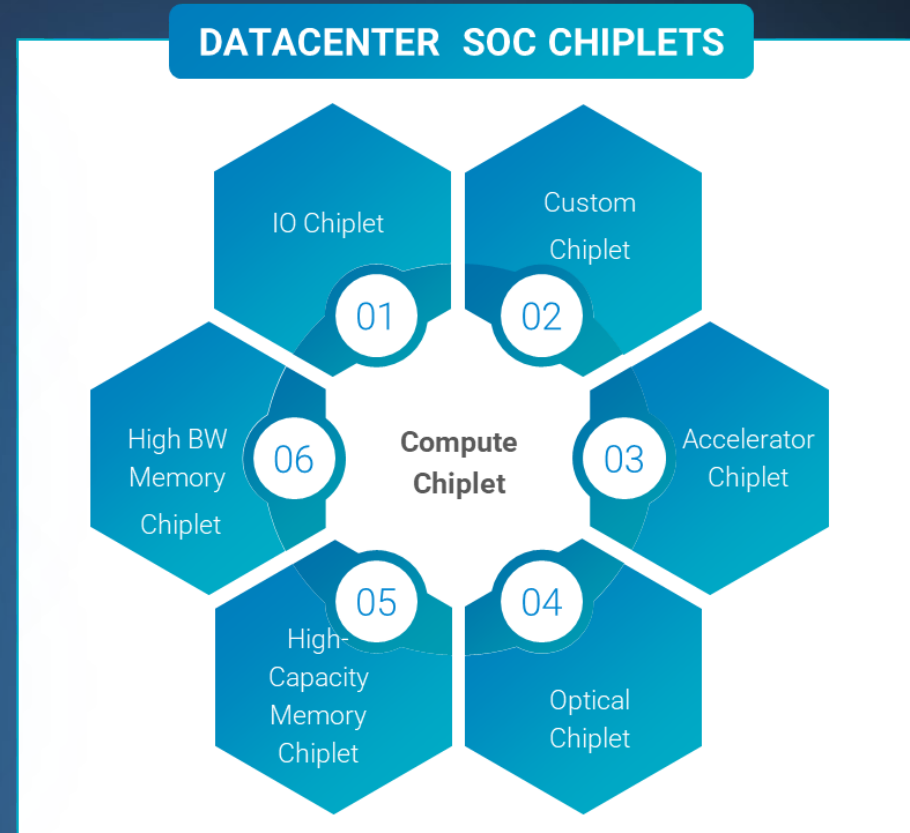
Wide acceptance of the Universal Chiplet Interconnect Express¹ (UCIe™) standard in 2022 to accelerate and democratize the chiplet ecosystem



IC design and package optimizations are the future for advanced compute semiconductors

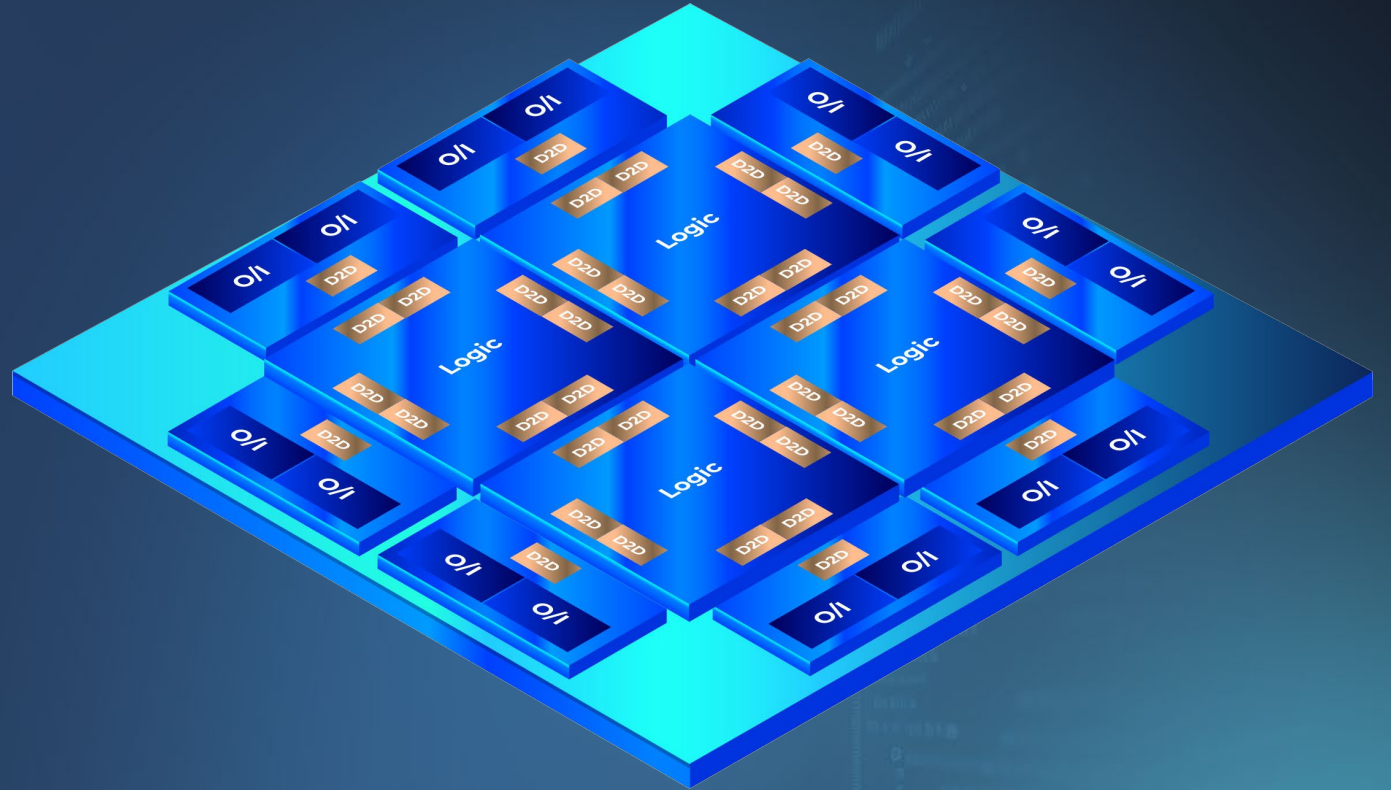


¹ <https://www.uciexpress.org/>

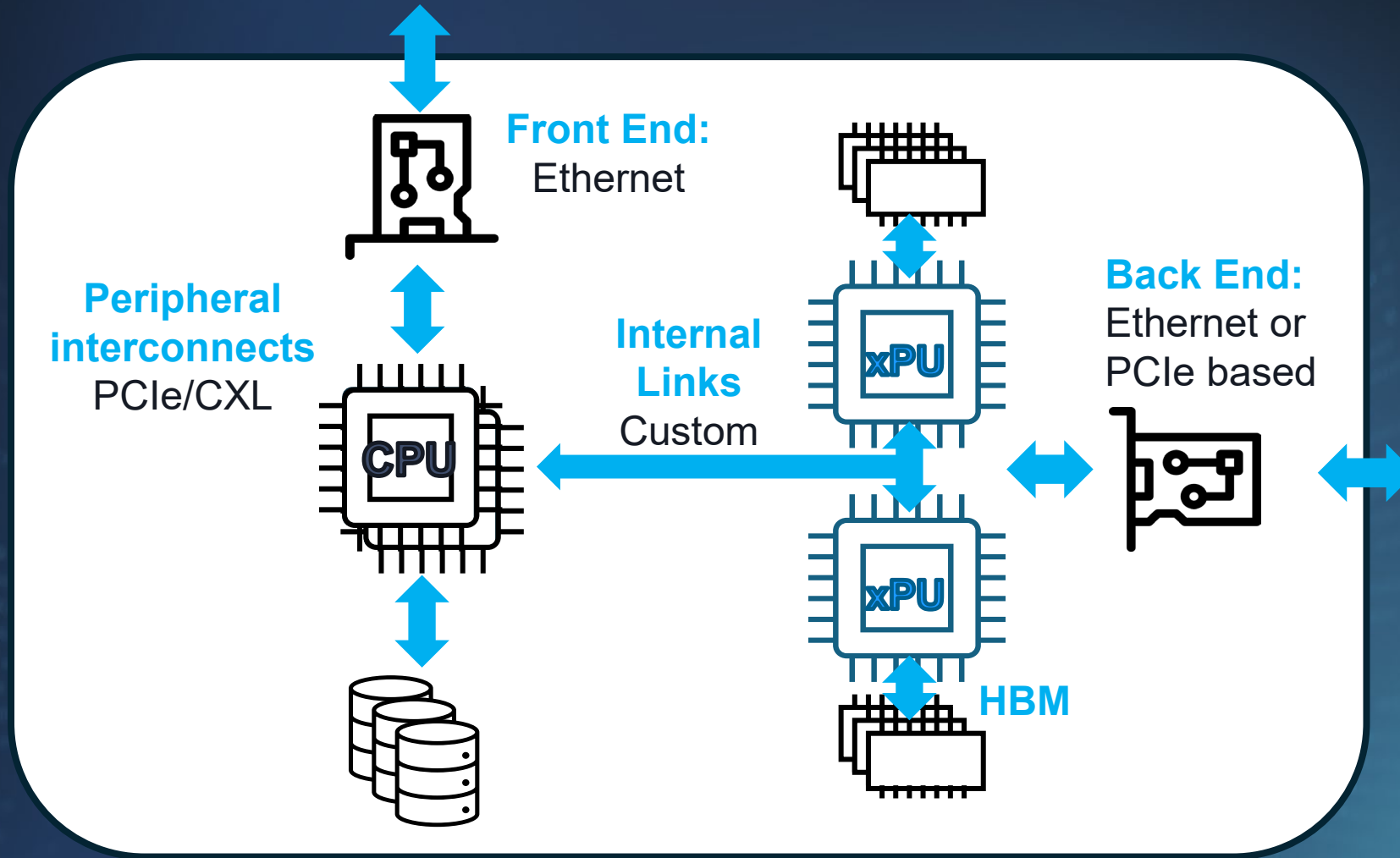


Chipllets: Accelerating the Adoption of Hardware Upgrades

- Reduced design time
- Reduced risk
- Composability



Full AI Connectivity Suite Needed for Designing at Scale

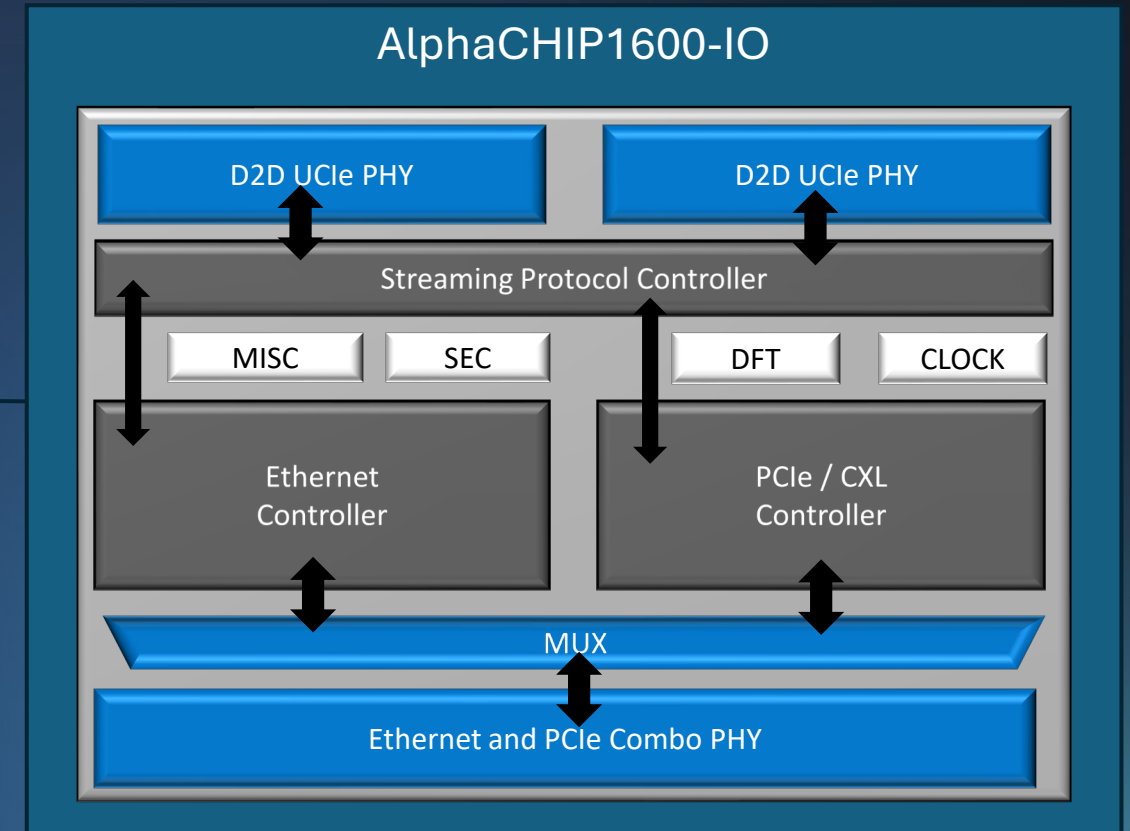
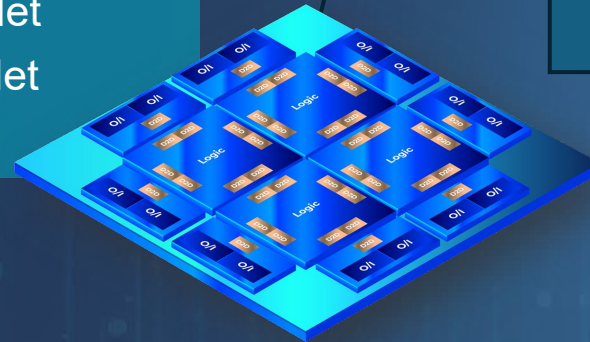


Industry First, Multi-Protocol I/O Connectivity Chiplet

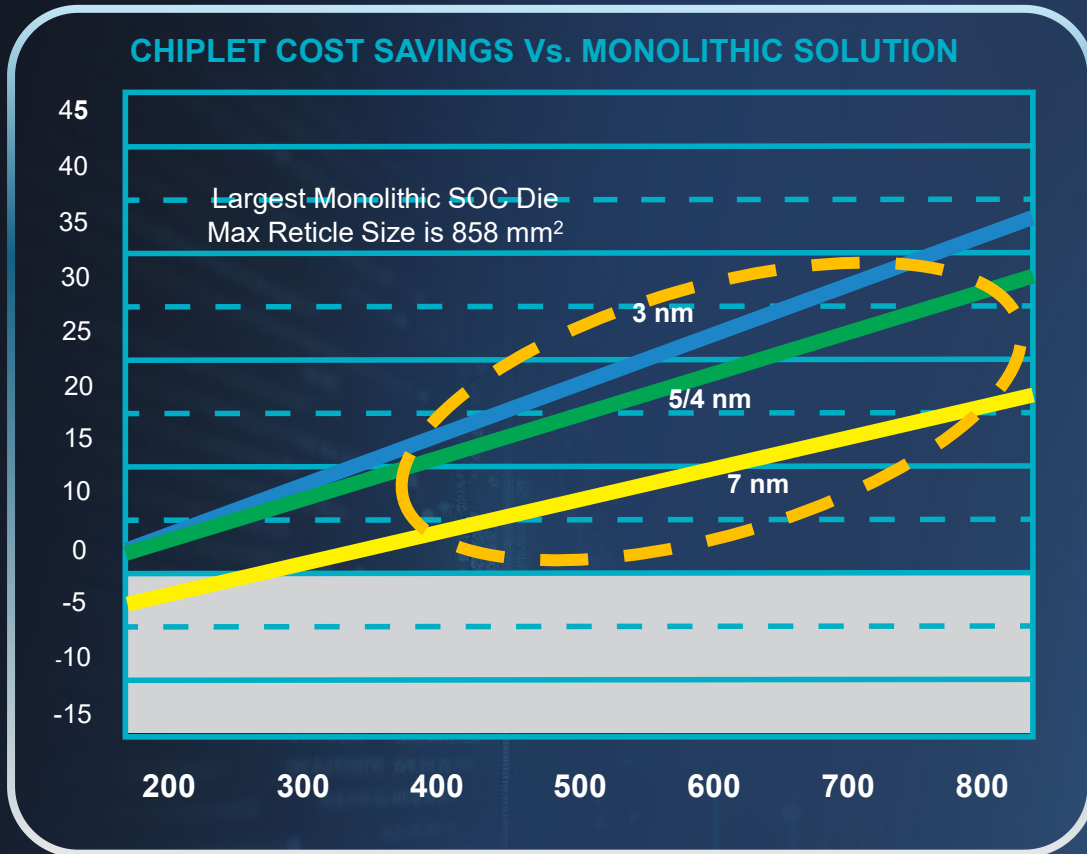
- AlphaCHIP1600-IO
 - Reconfigurable Multi-Standard 112G SerDes I/O
 - UCIe Compliant ver1.1 D2D interconnect
 - Integrated protocol controllers, security IP and UCIe PHY, and Controller IP that enables up to 1.6T of throughput at MR, XLR, and PCIe/CXL reach.

Application

- Medium Reach Optical Driver Chiplet
- Extra Long Reach Ethernet Chiplet
- Combo PCIe/CXL/Ethernet Chiplet
- 1.6T high-speed I/O Chiplet



Scaling Networking and Computing Barriers



Smaller Die

- Reduced die sizes, better yield

Up to 40%

lower die cost



Lower Non-Recurring Engineering Cost

- Mix and match chiplets from different nodes

Millions

saved in NRE \$



Lower Power

- Smaller die-to-die signal transfer (< 0.3 pJ/lane)
- Ability to optimize voltages for each chiplet separately

25–50%

reduction in power

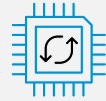


the Future of Memory and Storage



Custom Silicon

Spec-to-Silicon Capabilities
Advanced 2.5D/3D Packaging
Application Optimized IP
Subsystems



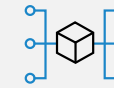
Silicon IP

High Performance
Connectivity IP
- PCIe/CXL
- Ethernet
- HBM/DDR



Chiplets

UCle™ Enable
- I/O Chiplet
- Memory Chiplet
- Compute Chiplet



Connectivity Products

Industry Leading
Electrical and Optical
PAM4 and Coherent DSPs

Thank You